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(71) Applicant: **MOMENTIVE PERFORMANCE MATERIALS INC.** [US/US]; 260 Hudson River Road, Waterford, Ohio 12188 (US).

(72) Inventors: **RUPPENTHAL, Andrea**; Damaschkestr. 30, 51373 Leverkusen (DE). **GROSSMANN, Matthias**; Gartenstrasse 8, 63808 Haibach (DE). **MISTRY, Umesh**; 117 Park Road, Prestwich, Manchester Greater Manchester M25 0DX (GB). **WILKEN, Karen**; Droste-Huelshoff-Strasse 12, 51519 Odenthal (DE).

(74) Agent: **SLABY, Scott M.**; MCDONALD HOPKINS LLC, 600 Superior Ave., Suite 2100, Cleveland, Ohio 44114 (US).

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(54) Title: A SILICONE COMPOSITION IN THE POTTING OF ELECTRONIC COMPONENTS

(57) Abstract: Provided is a composition that exhibits curing characteristics and can be cured by exposure to high energy conditions (i.e., photo-activatable) and optionally by exposure to non-photoactivatable conditions (e.g., condensation curing and/or at elevated temperatures). The present compositions are suitable for use as a potting compound in electronic applications and can be used as a material to fill space in and around electronic components. The compositions also display excellent adhesion to a variety of substrates. Also provided are methods of curing and using the compositions in various applications.

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